NST3906F3T5G

PNP General Purpose Transistor

The NST3906F3T5G device is a spin-off of our popular SOT-23/SOT-323/SOT-563/SOT-963 three-leaded device. It is designed for general purpose amplifier applications and is housed in the SOT-1123 surface mount package. This device is ideal for low-power surface mount applications where board space is at a premium.

Features

- h_{FE}, 100–300
- Low $V_{CE(sat)}$, $\leq 0.4 \text{ V}$
- Reduces Board Space
- This is a Pb–Free Device

MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector – Emitter Voltage	V _{CEO}	-40	Vdc
Collector – Base Voltage	V _{CBO}	-40	Vdc
Emitter-Base Voltage	V _{EBO}	-5.0	Vdc
Collector Current – Continuous	Ι _C	-200	mAdc

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 1)	290 2.3	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 1)	432	°C/W
Total Device Dissipation, T _A = 25°C Derate above 25°C	P _D (Note 2)	347 2.8	mW mW/°C
Thermal Resistance, Junction-to-Ambient	R _{θJA} (Note 2)	360	°C/W
Thermal Resistance, Junction-to-Lead 3	R _{ΨJL} (Note 2)	143	°C/W
Junction and Storage Temperature Range	T _J , T _{stg}	–55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

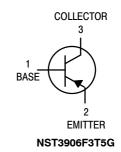
1. 100 mm² 1 oz, copper traces.

2. 500 mm² 1 oz, copper traces.

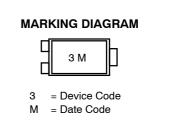


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http://onsemi.com







ORDERING INFORMATION

Device	Package	Shipping [†]
NST3906F3T5G	SOT-1123 (Pb-Free)	8000/Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NST3906F3T5G

ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

Characteristic	Symbol	Min	Max	Unit
OFF CHARACTERISTICS				
Collector – Emitter Breakdown Voltage (Note 3) ($I_C = 1.0 \text{ mAdc}, I_B = 0$)	V _{(BR)CEO}	-40	-	Vdc
Collector – Base Breakdown Voltage ($I_C = 10 \ \mu Adc$, $I_E = 0$)	V _{(BR)CBO}	-40	-	Vdc
Emitter – Base Breakdown Voltage (I_E = 10 μ Adc, I_C = 0)	V _{(BR)EBO}	-5.0	-	Vdc
Collector Cutoff Current (V _{CE} = 30 Vdc, V _{BE} = 3.0 Vdc)	I _{CEX}	-	-50	nAdc

ON CHARACTERISTICS (Note 3)

$ \begin{array}{l} \mbox{DC Current Gain} \\ (I_{C} = -0.1 \mbox{ mAdc}, V_{CE} = -1.0 \mbox{ Vdc}) \\ (I_{C} = -1.0 \mbox{ mAdc}, V_{CE} = -1.0 \mbox{ Vdc}) \\ (I_{C} = -10 \mbox{ mAdc}, V_{CE} = -1.0 \mbox{ Vdc}) \\ (I_{C} = -50 \mbox{ mAdc}, V_{CE} = -1.0 \mbox{ Vdc}) \\ (I_{C} = -100 \mbox{ mAdc}, V_{CE} = -1.0 \mbox{ Vdc}) \\ \end{array} $	h _{FE}	60 80 100 60 30	- - 300 - -	_
Collector – Emitter Saturation Voltage $(I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc})$ $(I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc})$	V _{CE(sat)}		-0.25 -0.4	Vdc
Base – Emitter Saturation Voltage ($I_C = -10 \text{ mAdc}, I_B = -1.0 \text{ mAdc}$) ($I_C = -50 \text{ mAdc}, I_B = -5.0 \text{ mAdc}$)	V _{BE(sat)}	-0.65 -	-0.85 -0.95	Vdc

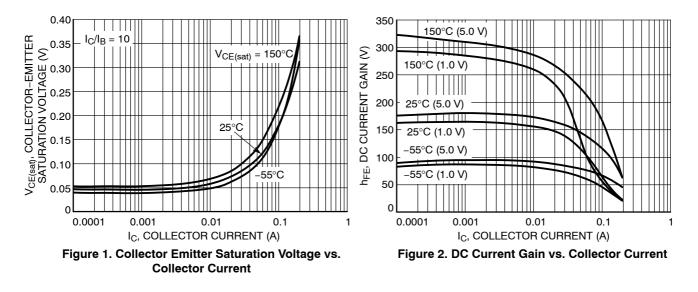
SMALL-SIGNAL CHARACTERISTICS

Current-Gain – Bandwidth Product (I_C = 10 mAdc, V_{CE} = 20 Vdc, f = 100 MHz)	f _T	250	-	MHz
Output Capacitance (V _{CB} = -5.0 V, I _E = 0 mA, f = 1.0 MHz)	C _{obo}	-	4.5	pF
Input Capacitance (V _{EB} = -0.5 V, I _E = 0 mA, f = 1.0 MHz)	C _{ibo}	-	10.0	pF
Noise Figure (V _{CE} = -5.0 Vdc, I _C = -100 μAdc, R _S = 1.0 kΩ, f = 1.0 kHz)	NF	-	4.0	dB

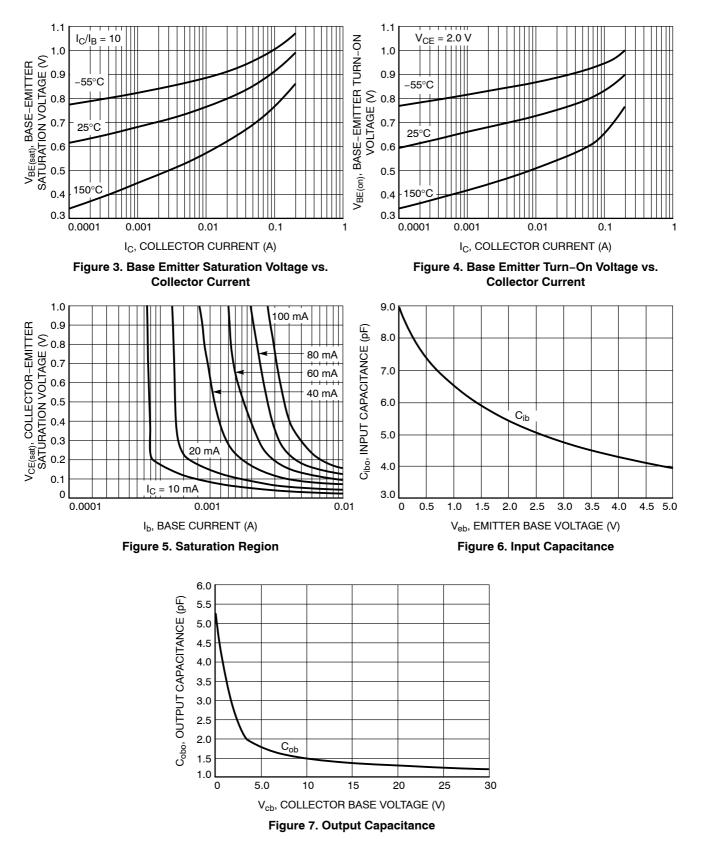
SWITCHING CHARACTERISTICS

Delay Time	$(V_{CC} = -3.0 \text{ Vdc}, V_{BE} = 0.5 \text{ Vdc})$	t _d	-	35	20
Rise Time	(I _C = -10 mAdc, I _{B1} = -1.0 mAdc)	t _r	-	35	ns
Storage Time	$(V_{CC} = -3.0 \text{ Vdc}, I_C = -10 \text{ mAdc})$	t _s	-	250	20
Fall Time	$(I_{B1} = I_{B2} = -1.0 \text{ mAdc})$	t _f	-	50	ns

3. Pulse Test: Pulse Width \leq 300 $\mu s;$ Duty Cycle \leq 2.0%.

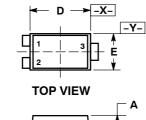


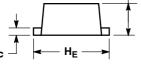
NST3906F3T5G



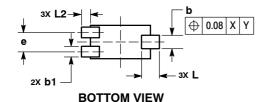
PACKAGE DIMENSIONS

SOT-1123 CASE 524AA ISSUE C









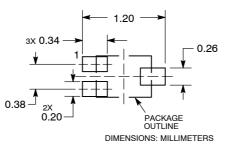
NOTES

- 1. DIMENSIONING AND TOLERANCING PER
- ASME Y14.5M, 1994. CONTROLLING DIMENSION: MILLIMETERS. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE З.
- MINIMUM THICKNESS OF BASE MATERIAL DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE 4.

MOL	D FLASI	1, PRUI	ł			
(BUR	BURRS.					
	MILLIM	MILLIMETERS				
DIM	MIN	MIN MAX				
Α	0.34	0.40				
b	0.15	0.28				
b1	0.10	0.20				
С	0.07	0.17				
D	0.75	0.85				
E	0.55	0.65				
е	0.35	0.40				
HE	0.95	1.05				
L	0.185 REF					
L2	0.05	0.15				

STYLE 1: PIN 1. BASE 2. EMITTER 3. COLLECTOR

SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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